IEEE *Xplore* ®
RELEASE 2.1

Welcome United States Patent and Trademark Office

⊏⊐⊒Search Session History   BROWSE   SEARCH   IEEE XPLORE GUIDE   SUPPORT

Edit an existing query or compose a new query in the Search Query Display.

Fri, 23 Jun 2006, 4:04:12 PM EST

Search Query Display

Select a search number (#) to:

- Add a query to the Search Query Display
- Combine search queries using AND, OR, or NOT
- Delete a search
- Run a search

Recent Search Queries   **Results**

#	Query	Results
#1	((wafer <near> fabrication and track and scanner) <in>metadata)	0
#2	((wafer and fabrication and track and scanner)<in>metadata)	0
#3	((wafer and fabrication)<in>metadata)	2550
#4	((((wafer and fabrication)<in>metadata))<AND>(track and scan*<in>metadata))	7
#5	((((((wafer and fabrication)<in>metadata)<and>(track and scan*<in>metadata)))<AND>(wait <near> states<in>metadata))	0
#6	((((((wafer and fabrication)<in>metadata)<and>(track and scan*<in>metadata)))<and>(pre-planned or planned<in>metadata))	1

Indexed by
Inspec®

IEEE *Xplore* ©
RELEASE 2.1

Welcome United States Patent and Trademark Office

⌐▢ **Search Results**

BROWSE   SEARCH   IEEE XPLORE GUIDE   SUPPORT

Results for "((((wafer and fabrication)<in>metadata))<and>(track and scan*<in>metadata))"
Your search matched **7** of **2550** documents.
A maximum of **100** results are displayed, **25** to a page, sorted by **Relevance** in **Descending** order.

✉ e-mail 🖷 printer friendly

» **Search Options**

View Session History

New Search

» **Key**

IEEE JNL	IEEE Journal or Magazine
IEE JNL	IEE Journal or Magazine
IEEE CNF	IEEE Conference Proceeding
IEE CNF	IEE Conference Proceeding
IEEE STD	IEEE Standard

Modify Search

((((wafer and fabrication)<in>metadata))<and>(track and scan*<in>metadata))   Search »

☐ Check to search only within this results set

Display Format: ◉ Citation ◯ Citation & Abstract

[view selected items]   Select All Deselect All

☐ 1. **A new solenoid magnetic integrated head for digital video recording**
Albertini, J.-B.; Sibuet, H.; Renaux, P.; Gaud, P.;
Magnetics, IEEE Transactions on
Volume 33, Issue 5, Part 1, Sept. 1997 Page(s):2836 - 2838
Digital Object Identifier 10.1109/20.617748

AbstractPlus | References | Full Text: PDF(700 KB)   IEEE JNL
Rights and Permissions

☐ 2. **Yield enhancement in photolithography through model-based process control: average mode control**
Grosman, B.; Lachman-Shalem, S.; Swissa, R.; Lewin, D.R.;
Semiconductor Manufacturing, IEEE Transactions on
Volume 18, Issue 1, Feb 2005 Page(s):86 - 93
Digital Object Identifier 10.1109/TSM.2004.836654

AbstractPlus | Full Text: PDF(488 KB)   IEEE JNL
Rights and Permissions

☐ 3. **Photoluminescence and photoreflectance scanning of silicon-on-insulator materials**
Hovel, H.J.;
SOI Conference, 1993. Proceedings., 1993 IEEE International
5-7 Oct. 1993 Page(s):26 - 27
Digital Object Identifier 10.1109/SOI.1993.344607

AbstractPlus | Full Text: PDF(248 KB)   IEEE CNF
Rights and Permissions

☐ 4. **Defect inspection sampling plans-which one is right for me?**
Scanlan, B.;
Advanced Semiconductor Manufacturing Conference and Workshop, 1998. 1998 IEEE/SEMI
23-25 Sept. 1998 Page(s):103 - 108
Digital Object Identifier 10.1109/ASMC.1998.731415

AbstractPlus | Full Text: PDF(660 KB)   IEEE CNF
Rights and Permissions

☐ 5. **Surface micromachined polyimide scanning thermocouple probes**
Li, M.-H.; Wu, J.J.; Gianchandani, Y.B.;
Microelectromechanical Systems, Journal of
Volume 10, Issue 1, March 2001 Page(s):3 - 9
Digital Object Identifier 10.1109/84.911085

AbstractPlus | References | Full Text: PDF(164 KB)   IEEE JNL
Rights and Permissions

6. **Monolithically cascaded micromirror pair driven by angular vertical combs for two-axis scanning**
Fujino, M.; Patterson, P.R.; Nguyen, H.; Piyawattanametha, W.; Wu, M.C.;
Selected Topics in Quantum Electronics, IEEE Journal of
Volume 10, Issue 3, May-June 2004 Page(s):492 - 497
Digital Object Identifier 10.1109/JSTQE.2004.829203

AbstractPlus | References | Full Text: PDF(320 KB)   IEEE JNL
Rights and Permissions

7. **Feature-scale Process Simulation and accurate capacitance extraction for the backend of a 100-nm aluminum/TEOS Process**
Heitzinger, C.; Sheikholeslami, A.; Badrieh, F.; Puchner, H.; Selberherr, S.;
Electron Devices, IEEE Transactions on
Volume 51, Issue 7, July 2004 Page(s):1129 - 1134
Digital Object Identifier 10.1109/TED.2004.829868

AbstractPlus | References | Full Text: PDF(488 KB)   IEEE JNL
Rights and Permissions

Help   Contact Us   Privacy & Security   IEEE.org

Indexed by
Inspec*

IEEE *Xplore*®
RELEASE 2.1

Welcome United States Patent and Trademark Office

Search Results   BROWSE   SEARCH   IEEE XPLORE GUIDE   SUPPORT

Results for "((((((wafer and fabrication)<in>metadata))<and>(track and scan*<in>metadata)))<..."   ☑ e-mail 🖨 printer friendly
Your search matched **1** of **1360403** documents.
A maximum of **100** results are displayed, **25** to a page, sorted by **Relevance** in **Descending** order.

» Search Options

View Session History

New Search

Modify Search

((((((wafer and fabrication)<in>metadata))<and>(track and scan*<in>metadata)))<an| Search >

☐ Check to search only within this results set

Display Format: ● Citation   ○ Citation & Abstract

» Key

IEEE JNL	IEEE Journal or Magazine
IEE JNL	IEE Journal or Magazine
IEEE CNF	IEEE Conference Proceeding
IEE CNF	IEE Conference Proceeding
IEEE STD	IEEE Standard

[view selected items]   **Select All Deselect All**

☐   1. **Defect inspection sampling plans-which one is right for me?**
Scanlan, B.;
Advanced Semiconductor Manufacturing Conference and Workshop, 1998. 1998 IEEE/SEMI
23-25 Sept. 1998 Page(s):103 - 108
Digital Object Identifier 10.1109/ASMC.1998.731415

AbstractPlus | Full Text: PDF(660 KB)   **IEEE CNF**
Rights and Permissions

Indexed by
Inspec°

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(semiconductor adj wafer near5 fabrication and track$3 and scanner and deviation and (planned pre-planned) near2 wait adj state$1 and avoid near conflict and compensat$3 and dynamically near2 insert$3 and time near delay)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:25
L2	1	(semiconductor adj wafer near5 fabrication and track$3 and scanner and deviation and (planned pre-planned) near2 wait adj state$1 and avoid near conflict and compensat$3 and dynamically near2 insert$3 and time near delay).clm.	US-PGPUB	OR	ON	2006/06/23 14:25
L3	13	("5455894" "2003045131" "6707545" "6308107" "2003099112").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L4	11	("5455894" "20030045131" "6707545" "6308107" "2003099112").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L5	0	L4 and clock with signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L6	0	L4 and clock	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L7	7	L4 and signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L8	2	L4 and timer$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26

EAST Search History

L9	4548	(700/121,204,112,99,247,258,259, 254 414/937,940).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L10	738	L9 and (semiconductor wafer) with (fabricat$3) and (inspect$3 monitor$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L11	129	L9 and (semiconductor wafer) with (fabricat$3) with (inspect$3 monitor$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L12	3	L9 and (semiconductor wafer) with (fabricat$3) with (inspect$3 monitor$3) and clock near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L13	0	L9 and (semiconductor wafer) with (fabricat$3) with (inspect$3 monitor$3) and clock near system	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L14	18	L9 and (semiconductor wafer) with (fabricat$3) and (inspect$3 monitor$3) and (scanner$1 camera$1) and clock$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L15	7	L9 and (semiconductor wafer) with (fabricat$3) and (inspect$3 monitor$3) and (scanner$1 camera$1) and (deviation variation) with (adjustment compensation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L16	372	(semiconductor wafer) with (fabricat$3) and (inspect$3 monitor$3) and (scanner$1 camera$1) and (deviation variation) with (adjustment compensation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L17	0	(semiconductor wafer) with (fabricat$3) and (inspect$3 monitor$3) and (scanner$1 camera$1) and (clock time) with delay with (deviation variation) with (adjustment compensation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26

L18	17	(semiconductor wafer) with (fabricat$3) and (inspect$3 monitor$3) and (scanner$1 camera$1) and (clock time) with (deviation variation) with (adjustment compensation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L19	25	oh near hilario.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L28	1	(semiconductor and fabrication).ab. and (scanner$1 camera) with system adj clock	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L29	0	(semiconductor and fabrication).ab. and (scanner$1 camera) with operating with (clock pulse$1) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L30	0	(semiconductor and fabrication).ab. and (scanner$1 camera) and operating with (clock pulse$1) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L31	1	(semiconductor and fabrication).ab. and (scan$$5 camera$1) and operating with (clock pulse$1) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L32	9	(semiconductor and fabrication).ab. and (scan$$5 camera$1) and operat$3 with (clock pulse$1) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L33	99	(semiconductor and fabrication).ab. and (scan$$5 camera$1) near system	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L34	9	(semiconductor and fabrication).ab. and (scan$$5 camera$1) near system and (clock pulse$1) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L35	1	2004-699555.NRAN.	DERWENT	OR	ON	2006/06/23 14:26

EAST Search History

L36	8	(semiconductor and fabrication).ab. and (scan$$5) near system and (track$3 near system)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L37	903	(semiconductor and fabrication).ab. and inspect$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L38	61	(semiconductor and fabrication).ab. and inspect$3 and time adj delay$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L39	42	(semiconductor and fabrication and inspect$3).ab. and time adj delay$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L40	42	(semiconductor and fabrication and inspect$3).ab. and time adj delay$3 and (scan$5 camera$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L41	2	(semiconductor and fabrication and inspect$3).ab. and time adj delay$3 and (scan$5 camera$1) and time near (calculation computation computing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L42	0	(semiconductor and fabrication and inspect$3).ab. and time adj delay$3 with (calculation computation computing) and (scan$5 camera$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L43	0	(semiconductor and fabrication and inspect$3).ab. and time adj delay$3 same (calculation computation computing) and (scan$5 camera$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L44	7	(semiconductor and fabrication and inspect$3).ab. and time same (calculation computation computing) and (scan$5 camera$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L45	571	(semiconductor and fabrication and inspect$3) and time with (calculation computation computing) and (scan$5 camera$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26

EAST Search History

L46	4	(semiconductor and fabrication and inspect$3) and time with (calculation computation computing) same (scan$5) with operat$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L47	1692	(semiconductor and fabrication and inspect$3) and scanner	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L48	5	(semiconductor and fabrication and inspect$3 and scanner).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L49	1773	(semiconductor and fabrication and inspect$3).ab. operating near scanner$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L50	452	(semiconductor and fabrication and inspect$3).ab. operating near scanner$1 with (clock pulse) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L51	448	(semiconductor and fabrication and inspect$3).ab. operating near scanner$1 with response with (clock pulse) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L52	0	(semiconductor and fabrication and inspect$3).ab. and operating near scanner$1 with response with (clock pulse) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L53	0	(semiconductor and fabrication and inspect$3).ab. and operating near scanner$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L54	4	semiconductor and fabrication and inspect$3 and operating near scanner$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L55	0	(wafer$1 and inspect$3).ab. and operating near scanner$1 with response with (clock pulse) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26

L56	0	(wafer$1 and inspect$3).ab. and operating near scanner$1 with (clock pulse) near signal$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L57	0	(wafer$1 and inspect$3).ab. and operating near scanner$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L58	0	(wafer$1 and monitor$3).ab. and operating near scanner$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L59	0	(semiconductor and monitor$3).ab. and operating near scanner$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L60	0	(semiconductor and inspect$3).ab. and operating near scanner$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L61	11	(semiconductor and inspect$3).ab. and scanner$1 near system	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L62	209	(semiconductor and inspect$3).ab. and time near delay$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L63	9	(semiconductor and inspect$3).ab. and time near delay$3 and time near (calculation calculating calculated computing computation calculates computes computed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L64	0	(semiconductor and inspect$3).ab. and scan$4 near delay$3 and time near (calculation calculating calculated computing computation calculates computes computed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L65	9	semiconductor and inspect$3 and scan$4 near delay$3 and time near (calculation calculating calculated computing computation calculates computes computed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26

L71	33	semiconductor and inspection near scanner	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L72	0	semiconductor and inspection near scanner and number adj of adj wafer$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L73	2	semiconductor and inspection near scanner and wafer$1 with count$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L76	615	wafer adj per adj hour	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L77	615	wafers adj per adj hour	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L78	2	(moving carrying transporting) near5 (wafer$ adj per adj hour)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L79	0	(moving carrying transporting) near5 (wafer$ near hour)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L80	0	(moving carrying transporting conveying) near5 (wafer$ near hour)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L81	6	(moving carrying transporting conveying) near5 (wafer$ near3 hour)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L82	0	(semiconductor with fabrication) and process$3 with speed and (number adj of amount adj of) near5 wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26

EAST Search History

L83	0	(semiconductor with fabrication) and process$3 with speed and (number adj of amount adj of) with wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L84	0	(semiconductor with fabrication) and scan$4 and (number adj of amount adj of) with wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L85	0	(semiconductor with fabrication) and scan$4 and (number adj of amount adj of) adj wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L86	10331	(semiconductor with fabrication) and scan$4 and wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L87	2500	(semiconductor with fabrication) and scan$4 and (number amount) near5 wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L88	0	(semiconductor with fabrication) and scan$4 and (number amount) adj of near5 wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L89	1064	(semiconductor with fabrication) and scan$4 and (number amount) near3 wafers and speed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L90	207	(semiconductor with fabrication) and scan$4 and (number amount) near3 wafers and scan$4 near3 speed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L91	22	(semiconductor with fabrication) and scan$4 with (number amount) near3 wafers and scan$4 near3 speed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26
L92	68	(semiconductor with fabrication) and scan$4 with (number amount) near3 wafers and throughput	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 14:26

EAST Search History

L96	3146	(700/121,99,112,204,247,254,258, 259).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 15:33
L97	1442	414/937,940.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/06/23 15:33

C:\Documents and Settings\TPham11\My Documents\EAST\Workspaces\10800369.wsp

Page 9